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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IEBus, SIO, UART/USART
Peripherals	DMA, PWM, WDT
Number of I/O	85
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30843fhfp-u5

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1.2 Performance Overview

Tables 1.1 and 1.2 list performance overview of the M32C/84 group (M32C/84, M32C/84T).

Table 1.1 M32C/84 Group (M32C/84, M32C/84T) Performance (144-Pin Package)

Characteristic		Performance	
		M32C/84	M32C/84T
CPU	Basic Instructions	108 instructions	
	Shortest Instruction Execution Time	31.3 ns (f(BCLK)=32 MHz, Vcc1=4.2 V to 5.5 V) 41.7 ns (f(BCLK)=24 MHz, Vcc1=3.0 V to 5.5 V)	31.3 ns (f(BCLK)=32 MHz, Vcc1=4.2 V to 5.5 V)
	Operation Mode	Single-chip mode, Memory expansion mode and Microprocessor mode	Single-chip mode
	Address Space	16 Mbytes	
	Memory Capacity	See Table 1.3	
Peripheral Function	I/O Port	123 I/O pins and 1 input pin	
	Multifunction Timer	Timer A: 16 bits x 5 channels, Timer B: 16 bits x 6 channels Three-phase motor control circuit	
	Intelligent I/O	Time measurement function or Waveform generating function: 16 bits x 8 channels Communication function (Clock synchronous serial I/O, Clock asynchronous serial I/O, HDLC data processing)	
	Serial I/O	5 Channels Clock synchronous serial I/O, Clock asynchronous serial I/O, IEBus ⁽¹⁾ , I ² C bus ⁽²⁾	
	CAN Module	1 channel Supporting CAN 2.0B specification	
	A/D Converter	10-bit A/D converter: 1 circuit, 34 channels	
	D/A Converter	8 bits x 2 channels	
	DMAC	4 channels	
	DMAC II	Can be activated by all peripheral function interrupt sources Immediate transfer, Calculation transfer and Chain transfer functions	
	CRC Calculation Circuit	CRC-CCITT	
	X/Y Converter	16 bits x 16 bits	
	Watchdog Timer	15 bits x 1 channel (with prescaler)	
	Interrupt	38 internal and 8 external sources, 5 software sources Interrupt priority level: 7	
	Clock Generation Circuit	4 circuits Main clock oscillation circuit(*), Sub clock oscillation circuit(*), On-chip oscillator, PLL frequency synthesizer (*)Equipped with a built-in feedback resistor. Ceramic resonator or crystal oscillator must be connected externally	
	Oscillation Stop Detect Function	Main clock oscillation stop detect function	
	Voltage Detection Circuit	Available (optional)	Not available ⁽⁴⁾
Electrical Characteristics	Supply Voltage	Vcc1=4.2 V to 5.5 V, Vcc2=3.0 V to Vcc1 (f(BCLK)=32 MHz) Vcc1=3.0 V to 5.5 V, Vcc2=3.0 V to Vcc1 (f(BCLK)=24 MHz)	Vcc1=Vcc2=4.2 V to 5.5 V, (f(BCLK)=32 MHz) ⁽³⁾
	Power Consumption	28 mA (Vcc1=Vcc2=5 V, f(BCLK)=32 MHz) 22 mA (Vcc1=Vcc2=3.3 V, f(BCLK)=24 MHz) 10μA (Vcc1=Vcc2=5 V, f(BCLK)=32 kHz, in wait mode)	28 mA (Vcc1=Vcc2=5 V, f(BCLK)=32 MHz) 10μA (Vcc1=Vcc2=5 V, f(BCLK)=32 kHz, in wait mode)
Flash Memory	Program/Erase Supply Voltage	3.3 V ± 0.3 V or 5.0 V ± 0.5 V	
	Program and Erase Endurance	100 times (all space)	
Operating Ambient Temperature		-20 to 85°C -40 to 85°C (optional)	-40 to 85°C (T version)
Package		144-pin plastic molded LOFP	

NOTES:

1. IEBus is a trademark of NEC Electronics Corporation.
2. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
3. The supply voltage of M32C/84T (High-reliability version) must be Vcc1=Vcc2.
4. The cold start-up/warm start-up determine function is available only at the user's option.

All options are on a request basis.

Table 1.4 Pin Characteristics for 144-Pin Package

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin	Intelligent I/O Pin	Analog Pin	Bus Control Pin ⁽¹⁾
1		P96			TxD4/SDA4/SRxD4		ANEX1	
2		P95			CLK4		ANEX0	
3		P94		TB4IN	CTS4/RTS4/SS4		DA1	
4		P93		TB3IN	CTS3/RTS3/SS3		DA0	
5		P92		TB2IN	TxD3/SDA3/SRxD3			
6		P91		TB1IN	RxD3/SCL3/STxD3			
7		P90		TB0IN	CLK3			
8		P146						
9		P145						
10		P144						
11		P143				INPC17/OUTC17		
12		P142				INPC16/OUTC16		
13		P141				INPC15/OUTC15		
14		P140				INPC14/OUTC14		
15	BYTE							
16	CNVSS							
17	X _{CIN}	P87						
18	X _{COU} T	P86						
19	RESET							
20	X _{OUT}							
21	V _{SS}							
22	X _{IN}							
23	V _{CC1}							
24		P85	NMI					
25		P84	INT2					
26		P83	INT1		CAN0IN			
27		P82	INT0		CAN0OUT			
28		P81		TA4IN/U		INPC15/OUTC15		
29		P80		TA4OUT/U		ISRxD0		
30		P77		TA3IN	CAN0IN	INPC14/OUTC14/ISCLK0		
31		P76		TA3OUT	CAN0OUT	INPC13/OUTC13/ISTxD0		
32		P75		TA2IN/W		INPC12/OUTC12/ISRxD1/BE1IN		
33		P74		TA2OUT/W		INPC11/OUTC11/ISCLK1		
34		P73		TA1IN/V	CTS2/RTS2/SS2	INPC10/OUTC10/ISTxD1/BE1OUT		
35		P72		TA1OUT/V	CLK2			
36		P71		TB5IN/TA0IN	RxD2/SCL2/STxD2	INPC17/OUTC17		
37		P70		TA0OUT	TxD2/SDA2/SRxD2	INPC16/OUTC16		
38		P67			TxD1/SDA1/SRxD1			
39	V _{CC1}							
40		P66			RxD1/SCL1/STxD1			
41	V _{SS}							
42		P65			CLK1			
43		P64			CTS1/RTS1/SS1			
44		P63			TxD0/SDA0/SRxD0			
45		P62			RxD0/SCL0/STxD0			
46		P61			CLK0			
47		P60			CTS0/RTS0/SS0			
48		P137						

NOTES:

1. Bus control pins in M32C/84T cannot be used.

Table 1.4 Pin Characteristics for 144-Pin Package (Continued)

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin	Intelligent I/O Pin	Analog Pin	Bus Control Pin
49		P13 ₆						
50		P13 ₅						
51		P13 ₄						
52		P5 ₇						$\overline{\text{RDY}}$
53		P5 ₆						$\overline{\text{ALE}}$
54		P5 ₅						$\overline{\text{HOLD}}$
55		P5 ₄						$\overline{\text{HLDA/ALE}}$
56		P13 ₃						
57	V _{SS}							
58		P13 ₂						
59	V _{CC2}							
60		P13 ₁						
61		P13 ₀						
62		P5 ₃						$\overline{\text{CLKOUT/BCLK/ALE}}$
63		P5 ₂						$\overline{\text{RD}}$
64		P5 ₁						$\overline{\text{WRH/BHE}}$
65		P5 ₀						$\overline{\text{WRL/WR}}$
66		P12 ₇						
67		P12 ₆						
68		P12 ₅						
69		P4 ₇						$\overline{\text{CS0/A23}}$
70		P4 ₆						$\overline{\text{CS1/A22}}$
71		P4 ₅						$\overline{\text{CS2/A21}}$
72		P4 ₄						$\overline{\text{CS3/A20}}$
73		P4 ₃						A ₁₉
74	V _{CC2}							
75		P4 ₂						A ₁₈
76	V _{SS}							
77		P4 ₁						A ₁₇
78		P4 ₀						A ₁₆
79		P3 ₇						A ₁₅ (/D ₁₅)
80		P3 ₆						A ₁₄ (/D ₁₄)
81		P3 ₅						A ₁₃ (/D ₁₃)
82		P3 ₄						A ₁₂ (/D ₁₂)
83		P3 ₃						A ₁₁ (/D ₁₁)
84		P3 ₂						A ₁₀ (/D ₁₀)
85		P3 ₁						A ₉ (/D ₉)
86		P12 ₄						
87		P12 ₃						
88		P12 ₂						
89		P12 ₁						
90		P12 ₀						
91	V _{CC2}							
92		P3 ₀						A ₈ (/D ₈)
93	V _{SS}							
94		P2 ₇					AN2 ₇	A ₇ (/D ₇)
95		P2 ₆					AN2 ₆	A ₆ (/D ₆)
96		P2 ₅					AN2 ₅	A ₅ (/D ₅)

NOTES:

1. Bus control pins in M32C/84T cannot be used.

Table 1.5 Pin Characteristics for 100-Pin Package (Continued)

Package Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin	Intelligent I/O Pin	Analog Pin	Bus Control Pin
FP	GP								
51	49		P43						A19
52	50		P42						A18
53	51		P41						A17
54	52		P40						A16
55	53		P37						A15(/D15)
56	54		P36						A14(/D14)
57	55		P35						A13(/D13)
58	56		P34						A12(/D12)
59	57		P33						A11(/D11)
60	58		P32						A10(/D10)
61	59		P31						A9(/D9)
62	60	Vcc2							
63	61		P30						A8(/D8)
64	62	Vss							
65	63		P27					AN27	A7(/D7)
66	64		P26					AN26	A6(/D6)
67	65		P25					AN25	A5(/D5)
68	66		P24					AN24	A4(/D4)
69	67		P23					AN23	A3(/D3)
70	68		P22					AN22	A2(/D2)
71	69		P21					AN21	A1(/D1)
72	70		P20					AN20	A0(/D0)
73	71		P17	INT5					D15
74	72		P16	INT4					D14
75	73		P15	INT3					D13
76	74		P14						D12
77	75		P13						D11
78	76		P12						D10
79	77		P11						D9
80	78		P10						D8
81	79		P07					AN07	D7
82	80		P06					AN06	D6
83	81		P05					AN05	D5
84	82		P04					AN04	D4
85	83		P03					AN03	D3
86	84		P02					AN02	D2
87	85		P01					AN01	D1
88	86		P00					AN00	D0
89	87		P107	KI3				AN7	
90	88		P106	KI2				AN6	
91	89		P105	KI1				AN5	
92	90		P104	KI0				AN4	
93	91		P103					AN3	
94	92		P102					AN2	
95	93		P101					AN1	
96	94	AVss							
97	95		P100					AN0	
98	96	VREF							
99	97	AVcc							
100	98		P97			RxD4/SCL4/STxD4		ADTRG	

NOTES:

1. Bus control pins in M32C/84T cannot be used.

Table 1.6 Pin Description (144-Pin Package only) (Continued)

Classsification	Symbol	I/O Type	Supply Voltage	Function
A/D Converter	AN150 to AN157	I	Vcc1	Analog input pins for the A/D converter
I/O Ports	P110 to P114 P120 to P127 P130 to P137	I/O	Vcc2	I/O ports having equivalent functions to P0
	P140 to P146 P150 to P157	I/O	Vcc1	I/O ports having equivalent functions to P0

I : Input O : Output I/O : Input and output

2.1.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is set to "0". The register bank 1 is selected when this flag is set to "1".

2.1.8.6 Overflow Flag (O)

The O flag is set to "1" when the result of an arithmetic operation overflows; otherwise "0".

2.1.8.7 Interrupt Enable Flag (I)

The I flag enables a maskable interrupt.

Interrupt is disabled when the I flag is set to "0" and enabled when the I flag is set to "1". The I flag is set to "0" when an interrupt is acknowledged.

2.1.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to "0". USP is selected when this flag is set to "1".

The U flag is set to "0" when a hardware interrupt is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.1.8.9 Processor Interrupt Priority Level (IPL)

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has greater priority than IPL, the interrupt is enabled.

2.1.8.10 Reserved Space

When writing to a reserved space, set to "0". When reading, its content is indeterminate.

2.2 High-Speed Interrupt Registers

Registers associated with the high-speed interrupt are as follows:

- Flag save register (SVF)
- PC save register (SVP)
- Vector register (VCT)

2.3 DMAC-Associated Registers

Registers associated with DMAC are as follows:

- DMA mode register (DMD0, DMD1)
- DMA transfer count register (DCT0, DCT1)
- DMA transfer count reload register (DRC0, DRC1)
- DMA memory address register (DMA0, DMA1)
- DMA SFR address register (DSA0, DSA1)
- DMA memory address reload register (DRA0, DRA1)

Address	Register	Symbol	Value after RESET
0150 ₁₆			
0151 ₁₆			
0152 ₁₆			
0153 ₁₆			
0154 ₁₆			
0155 ₁₆			
0156 ₁₆			
0157 ₁₆			
0158 ₁₆			
0159 ₁₆			
015A ₁₆			
015B ₁₆			
015C ₁₆			
015D ₁₆			
015E ₁₆			
015F ₁₆			
0160 ₁₆			
0161 ₁₆			
0162 ₁₆			
0163 ₁₆			
0164 ₁₆			
0165 ₁₆			
0166 ₁₆			
0167 ₁₆			
0168 ₁₆			
0169 ₁₆			
016A ₁₆			
016B ₁₆			
016C ₁₆			
016D ₁₆			
016E ₁₆			
016F ₁₆			
0170 ₁₆			
0171 ₁₆			
0172 ₁₆			
0173 ₁₆			
0174 ₁₆			
0175 ₁₆			
0176 ₁₆			
0177 ₁₆			
0178 ₁₆	Input Function Select Register	IPS	00 ₁₆
0179 ₁₆	Input Function Select Register A	IPSA	00 ₁₆
017A ₁₆			
017B ₁₆			
017C ₁₆			
017D ₁₆ to 01DF ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

Address	Register	Symbol	Value after RESET
01E0 ₁₆	CAN0 Message Slot Buffer 0 Standard ID0	C0SLOT0_0	XX ₁₆
01E1 ₁₆	CAN0 Message Slot Buffer 0 Standard ID1	C0SLOT0_1	XX ₁₆
01E2 ₁₆	CAN0 Message Slot Buffer 0 Extended ID0	C0SLOT0_2	XX ₁₆
01E3 ₁₆	CAN0 Message Slot Buffer 0 Extended ID1	C0SLOT0_3	XX ₁₆
01E4 ₁₆	CAN0 Message Slot Buffer 0 Extended ID2	C0SLOT0_4	XX ₁₆
01E5 ₁₆	CAN0 Message Slot Buffer 0 Data Length Code	C0SLOT0_5	XX ₁₆
01E6 ₁₆	CAN0 Message Slot Buffer 0 Data 0	C0SLOT0_6	XX ₁₆
01E7 ₁₆	CAN0 Message Slot Buffer 0 Data 1	C0SLOT0_7	XX ₁₆
01E8 ₁₆	CAN0 Message Slot Buffer 0 Data 2	C0SLOT0_8	XX ₁₆
01E9 ₁₆	CAN0 Message Slot Buffer 0 Data 3	C0SLOT0_9	XX ₁₆
01EA ₁₆	CAN0 Message Slot Buffer 0 Data 4	C0SLOT0_10	XX ₁₆
01EB ₁₆	CAN0 Message Slot Buffer 0 Data 5	C0SLOT0_11	XX ₁₆
01EC ₁₆	CAN0 Message Slot Buffer 0 Data 6	C0SLOT0_12	XX ₁₆
01ED ₁₆	CAN0 Message Slot Buffer 0 Data 7	C0SLOT0_13	XX ₁₆
01EE ₁₆	CAN0 Message Slot Buffer 0 Time Stamp High-Order	C0SLOT0_14	XX ₁₆
01EF ₁₆	CAN0 Message Slot Buffer 0 Time Stamp Low-Order	C0SLOT0_15	XX ₁₆
01F0 ₁₆	CAN0 Message Slot Buffer 1 Standard ID0	C0SLOT1_0	XX ₁₆
01F1 ₁₆	CAN0 Message Slot Buffer 1 Standard ID1	C0SLOT1_1	XX ₁₆
01F2 ₁₆	CAN0 Message Slot Buffer 1 Extended ID0	C0SLOT1_2	XX ₁₆
01F3 ₁₆	CAN0 Message Slot Buffer 1 Extended ID1	C0SLOT1_3	XX ₁₆
01F4 ₁₆	CAN0 Message Slot Buffer 1 Extended ID2	C0SLOT1_4	XX ₁₆
01F5 ₁₆	CAN0 Message Slot Buffer 1 Data Length Code	C0SLOT1_5	XX ₁₆
01F6 ₁₆	CAN0 Message Slot Buffer 1 Data 0	C0SLOT1_6	XX ₁₆
01F7 ₁₆	CAN0 Message Slot Buffer 1 Data 1	C0SLOT1_7	XX ₁₆
01F8 ₁₆	CAN0 Message Slot Buffer 1 Data 2	C0SLOT1_8	XX ₁₆
01F9 ₁₆	CAN0 Message Slot Buffer 1 Data 3	C0SLOT1_9	XX ₁₆
01FA ₁₆	CAN0 Message Slot Buffer 1 Data 4	C0SLOT1_10	XX ₁₆
01FB ₁₆	CAN0 Message Slot Buffer 1 Data 5	C0SLOT1_11	XX ₁₆
01FC ₁₆	CAN0 Message Slot Buffer 1 Data 6	C0SLOT1_12	XX ₁₆
01FD ₁₆	CAN0 Message Slot Buffer 1 Data 7	C0SLOT1_13	XX ₁₆
01FE ₁₆	CAN0 Message Slot Buffer 1 Time Stamp High-Order	C0SLOT1_14	XX ₁₆
01FF ₁₆	CAN0 Message Slot Buffer 1 Time Stamp Low-Order	C0SLOT1_15	XX ₁₆
0200 ₁₆ 0201 ₁₆	CAN0 Control Register 0	C0CTRL0	XX01 0X01 ₂ ⁽¹⁾ XXXX 0000 ₂ ⁽¹⁾
0202 ₁₆ 0203 ₁₆	CAN0 Status Register	C0STR	0000 0000 ₂ ⁽¹⁾ X000 0X01 ₂ ⁽¹⁾
0204 ₁₆ 0205 ₁₆	CAN0 Extended ID Register	C0IDR	00 ₁₆ ⁽¹⁾ 00 ₁₆ ⁽¹⁾
0206 ₁₆ 0207 ₁₆	CAN0 Configuration Register	C0CONR	0000 XXXX ₂ ⁽¹⁾ 0000 0000 ₂ ⁽¹⁾
0208 ₁₆ 0209 ₁₆	CAN0 Time Stamp Register	C0TSR	00 ₁₆ ⁽¹⁾ 00 ₁₆ ⁽¹⁾
020A ₁₆	CAN0 Transmit Error Count Register	C0TEC	00 ₁₆ ⁽¹⁾
020B ₁₆	CAN0 Receive Error Count Register	C0REC	00 ₁₆ ⁽¹⁾
020C ₁₆ 020D ₁₆	CAN0 Slot Interrupt Status Register	C0SISTR	00 ₁₆ ⁽¹⁾ 00 ₁₆ ⁽¹⁾
020E ₁₆			
020F ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

NOTES:

1. Values are obtained by setting the SLEEP bit in the C0SLPR register to "1" (sleep mode exited) after reset and supplying the clock to the CAN module.

Address	Register	Symbol	Value after RESET
0210 ₁₆	CAN0 Slot Interrupt Mask Register	C0SIMKR	00 ₁₆ ⁽²⁾
0211 ₁₆			00 ₁₆ ⁽²⁾
0212 ₁₆			
0213 ₁₆			
0214 ₁₆	CAN0 Error Interrupt Mask Register	C0EIMKR	XXXX X000 ₂ ⁽²⁾
0215 ₁₆	CAN0 Error Interrupt Status Register	C0EISTR	XXXX X000 ₂ ⁽²⁾
0216 ₁₆	CAN0 Error Cause Register	C0EFR	00 ₁₆ ⁽²⁾
0217 ₁₆	CAN0 Baud Rate Prescaler	C0BRP	0000 0001 ₂ ⁽²⁾
0218 ₁₆			
0219 ₁₆	CAN0 Mode Register	C0MDR	XXXX XX00 ₂ ⁽²⁾
021A ₁₆			
021B ₁₆			
021C ₁₆			
021D ₁₆			
021E ₁₆			
021F ₁₆			
0220 ₁₆	CAN0 Single-Shot Control Register	C0SSCTLR	00 ₁₆ ⁽²⁾
0221 ₁₆			00 ₁₆ ⁽²⁾
0222 ₁₆			
0223 ₁₆			
0224 ₁₆	CAN0 Single-Shot Status Register	C0SSSTR	00 ₁₆ ⁽²⁾
0225 ₁₆			00 ₁₆ ⁽²⁾
0226 ₁₆			
0227 ₁₆			
0228 ₁₆	CAN0 Global Mask Register Standard ID0	C0GMR0	XXX0 0000 ₂ ⁽²⁾
0229 ₁₆	CAN0 Global Mask Register Standard ID1	C0GMR1	XX00 0000 ₂ ⁽²⁾
022A ₁₆	CAN0 Global Mask Register Extended ID0	C0GMR2	XXXX 0000 ₂ ⁽²⁾
022B ₁₆	CAN0 Global Mask Register Extended ID1	C0GMR3	00 ₁₆ ⁽²⁾
022C ₁₆	CAN0 Global Mask Register Extended ID2	C0GMR4	XX00 0000 ₂ ⁽²⁾
022D ₁₆			
022E ₁₆			
022F ₁₆			
0230 ₁₆	CAN0 Message Slot 0 Control Register /	C0MCTL0/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Standard ID0	C0LMAR0	XXX0 0000 ₂ ⁽²⁾
0231 ₁₆	CAN0 Message Slot 1 Control Register /	C0MCTL1/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Standard ID1	C0LMAR1	XX00 0000 ₂ ⁽²⁾
0232 ₁₆	CAN0 Message Slot 2 Control Register /	C0MCTL2/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Extended ID0	C0LMAR2	XXXX 0000 ₂ ⁽²⁾
0233 ₁₆	CAN0 Message Slot 3 Control Register /	C0MCTL3/	00 ₁₆ ⁽²⁾
	CAN0 local Mask Register A Extended ID1	C0LMAR3	00 ₁₆ ⁽²⁾
0234 ₁₆	CAN0 Message Slot 4 Control Register /	C0MCTL4/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Extended ID2	C0LMAR4	XX00 0000 ₂ ⁽²⁾
0235 ₁₆	CAN0 Message Slot 5 Control Register	C0MCTL5	00 ₁₆ ⁽²⁾
0236 ₁₆	CAN0 Message Slot 6 Control Register	C0MCTL6	00 ₁₆ ⁽²⁾
0237 ₁₆	CAN0 Message Slot 7 Control Register	C0MCTL7	00 ₁₆ ⁽²⁾
0238 ₁₆	CAN0 Message Slot 8 Control Register /	C0MCTL8/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register B Standard ID0	C0LMBR0	XXX0 0000 ₂ ⁽²⁾

(Note 1)

X: Indeterminate

Blank spaces are reserved. No access is allowed.

NOTES:

1. The BANKSEL bit in the C0CTLR1 register switches functions for addresses 0220₁₆ to 023F₁₆.
2. Values are obtained by setting the SLEEP bit in the C0SLPR register to "1" (sleep mode exited) after reset and supplying the clock to the CAN module.

$$V_{CC1}=V_{CC2}=5V$$

Switching Characteristics

($V_{CC} = 4.2$ to $5.5V$, $V_{SS} = 0V$ at $T_{opr} = -20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.23 Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space with the multiplexed bus)

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address Output Delay Time	See Figure 5.2		18	ns
$t_{h(BCLK-AD)}$	Address Output Hold Time (BCLK standard)		-3		ns
$t_{h(RD-AD)}$	Address Output Hold Time (RD standard) ⁽⁵⁾		(Note 1)		ns
$t_{h(WR-AD)}$	Address Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
$t_{d(BCLK-CS)}$	Chip-Select Signal Output Delay Time			18	ns
$t_{h(BCLK-CS)}$	Chip-Select Signal Output Hold Time (BCLK standard)		-3		ns
$t_{h(RD-CS)}$	Chip-Select Signal Output Hold Time (RD standard) ⁽⁵⁾		(Note 1)		ns
$t_{h(WR-CS)}$	Chip-Select Signal Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
$t_{d(BCLK-RD)}$	RD Signal Output Delay Time			18	ns
$t_{h(BCLK-RD)}$	RD Signal Output Hold Time		-5		ns
$t_{d(BCLK-WR)}$	WR Signal Output Delay Time			18	ns
$t_{h(BCLK-WR)}$	WR Signal Output Hold Time		-5		ns
$t_{d(DB-WR)}$	Data Output Delay Time (WR standard)		(Note 2)		ns
$t_{h(WR-DB)}$	Data Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
$t_{d(BCLK-ALE)}$	ALE Signal Output Delay Time (BCLK standard)			18	ns
$t_{h(BCLK-ALE)}$	ALE Signal Output Hold Time (BCLK standard)		-2		ns
$t_{d(AD-ALE)}$	ALE Signal Output Delay Time (address standard)		(Note 3)		ns
$t_{h(ALE-AD)}$	ALE Signal Output Hold Time (address standard)		(Note 4)		ns
$t_{dZ(RD-AD)}$	Address Output Float Start Time			8	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency.

$$t_{h(RD-AD)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(WR-AD)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(RD-CS)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(WR-CS)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(WR-DB)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

2. Values can be obtained from the following equations, according to BCLK frequency and external bus cycle.

$$t_{d(DB-WR)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 25 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, m = (bx2)-1)$$

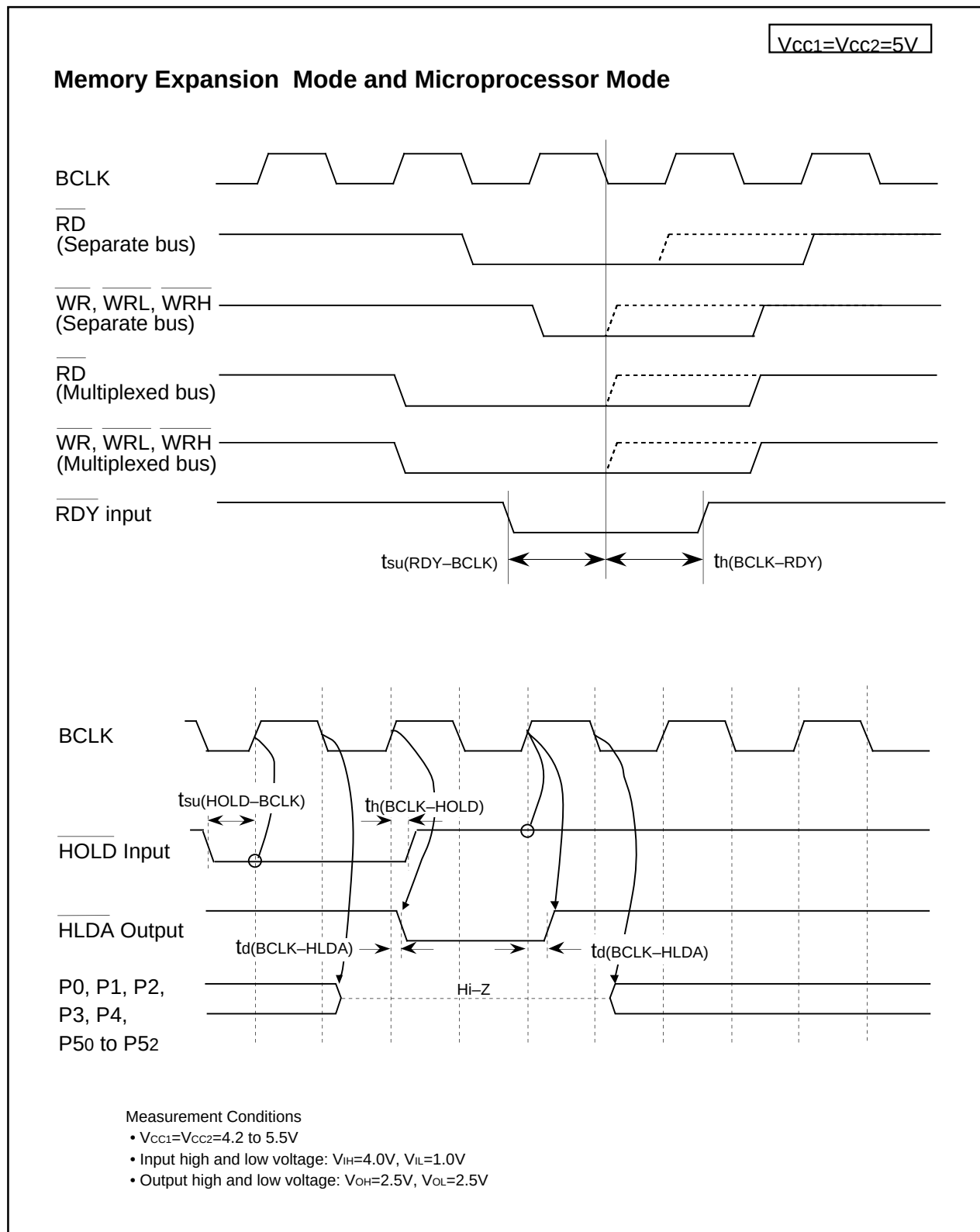
3. Values can be obtained from the following equations, according to BCLK frequency and external bus cycle.

$$t_{d(AD-ALE)} = \frac{10^9 \times n}{f_{(BCLK)} \times 2} - 20 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, n = a)$$

4. Values can be obtained from the following equations, according to BCLK frequency and external bus cycle.

$$t_{h(ALE-AD)} = \frac{10^9 \times n}{f_{(BCLK)} \times 2} - 10 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, n = a)$$

5. t_c ns is added when recovery cycle is inserted.

Figure 5.6 $V_{CC1}=V_{CC2}=5V$ Timing Diagram (4)

$$V_{CC1}=V_{CC2}=3.3V$$

Table 5.24 Electrical Characteristics ($V_{CC1}=V_{CC2}=3.0$ to $3.6V$, $V_{SS}=0V$ at $T_{opr} = -20$ to $85^{\circ}C$,
 $f(BCLK)=24MHz$ unless otherwise specified)

Symbol	Parameter			Condition		Standard			Unit
						Min.	Typ.	Max.	
V _{OH}	Output High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P110-P114, P120-P127, P130-P137		I _{OH} =-1mA	V _{CC2} -0.6		V _{CC2}	V	
		P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P140-P146, P150-P157 ⁽¹⁾			V _{CC1} -0.6		V _{CC1}	V	
		X _{OUT}		I _{OH} =-0.1mA	2.7		V _{CC1}	V	
		X _{COUT}	High Power	No load applied		2.5		V	
			Low Power	No load applied		1.6		V	
V _{OL}	Output Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾		I _{OL} =1mA			0.5	V	
		X _{OUT}		I _{OL} =0.1mA			0.5	V	
		X _{COUT}	High Power	No load applied		0		V	
			Low Power	No load applied		0		V	
		V _{T+} -V _{T-}	Hysteresis	HOLD, RDY, TA0 _{IN} -TA4 _{IN} , TB0 _{IN} -TB5 _{IN} , INT0-INT5, AD _{TRG} , CTS0-CTS4, CLK0-CLK4, TA0 _{OUT} -TA4 _{OUT} , NMI, KI0-KI3, RxD0-RxD4, SCL0-SCL4, SDA0-SDA4			0.2		1.0
		RESET			0.2		1.8	V	
I _{IH}	Input High ("H") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE		V _I =3V			4.0	μA	
I _{IL}	Input Low ("L") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE		V _I =0V			-4.0	μA	
R _{PULLUP}	Pull-up Resistance	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾		V _I =0V	Flash Memory	66	120	500	kΩ
					Masked ROM	40	70	500	kΩ
R _{fXIN}	Feedback Resistance	X _{IN}					3.0		MΩ
R _{fXCIN}	Feedback Resistance	X _{CIN}					20.0		MΩ
V _{RAM}	RAM Standby Voltage	in stop mode				2.0			V
I _{CC}	Power Supply Current	Measurement condition: In single-chip mode, output pins are left open and other pins are connected to V _{SS} .		f(BCLK)=24 MHz, Square wave, No division			22	35	mA
				f(BCLK)=32 kHz, In wait mode, T _{opr} =25° C			10		μA
				While clock stops, T _{opr} =25° C			0.8	5	μA
				While clock stops, T _{opr} =85° C				50	μA

NOTES:

1. P11 to P15 are provided in the 144-pin package only.

$$V_{CC1}=V_{CC2}=3.3V$$

**Table 5.25 A/D Conversion Characteristics ($V_{CC1}=V_{CC2}=AV_{CC}=V_{REF}=3.0$ to $3.6V$, $V_{SS}=AV_{SS}=0V$
at $T_{opr} = -20$ to $85^{\circ}C$, $f(BCLK) = 24MHz$ unless otherwise specified)**

Symbol	Parameter		Measurement Condition	Standard			Unit
				Min.	Typ.	Max.	
-	Resolution		$V_{REF}=V_{CC1}$			10	Bits
INL	Integral Nonlinearity Error	No S&H (8-bit)	$V_{CC1}=V_{CC2}=V_{REF}=3.3V$			± 2	LSB
DNL	Differential Nonlinearity Error	No S&H (8-bit)				± 1	LSB
-	Offset Error	No S&H (8-bit)				± 2	LSB
-	Gain Error	No S&H (8-bit)				± 2	LSB
RLADDER	Resistor Ladder		$V_{REF}=V_{CC1}$	8		40	k Ω
tCONV	8-bit Conversion Time ^(1, 2)			6.1			μs
VREF	Reference Voltage			3		V_{CC1}	V
VIA	Analog Input Voltage			0		V_{REF}	V

S&H: Sample and Hold

NOTES:

1. Divide $f(X_{IN})$, if exceeding 10 MHz, to keep ϕ_{AD} frequency at 10 MHz or less.
2. S&H not available.

**Table 5.26 D/A Conversion Characteristics ($V_{CC1}=V_{CC2}=V_{REF}=3.0$ to $3.6V$, $V_{SS}=AV_{SS}=0V$
at $T_{opr} = -20$ to $85^{\circ}C$, $f(BCLK) = 24MHz$ unless otherwise specified)**

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min.	Typ.	Max.	
-	Resolution				8	Bits
-	Absolute Accuracy				1.0	%
tsu	Setup Time				3	μs
Ro	Output Resistance		4	10	20	k Ω
IvREF	Reference Power Supply Input Current	(Note 1)			1.0	mA

NOTES:

1. Measurement results when using one D/A converter. The DAi register (i=0, 1) of the D/A converter, not being used, is set to "00₁₆". The resistor ladder in the A/D converter is excluded.
IvREF flows even if the VCUT bit in the AD0CON1 register is set to "0" (no VREF connection).

$$V_{CC1}=V_{CC2}=3.3V$$

Timing Requirements

($V_{CC1}=V_{CC2}= 3.0$ to $3.6V$, $V_{SS} = 0V$ at $T_{opr} = -20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.27 External Clock Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	41		ns
$t_{w(H)}$	External Clock Input High ("H") Width	18		ns
$t_{w(L)}$	External Clock Input Low ("L") Width	18		ns
t_r	External Clock Rise Time		5	ns
t_f	External Clock Fall Time		5	ns

Table 5.28 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data Input Access Time (RD standard)		(Note 1)	ns
$t_{ac1(AD-DB)}$	Data Input Access Time (AD standard, CS standard)		(Note 1)	ns
$t_{ac2(RD-DB)}$	Data Input Access Time (RD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
$t_{ac2(AD-DB)}$	Data Input Access Time (AD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
$t_{su(DB-BCLK)}$	Data Input Setup Time	30		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ Input Setup Time	40		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ Input Setup Time	60		ns
$t_{h(RD-DB)}$	Data Input Hold Time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ Input Hold Time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ Input Hold Time	0		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ Output Delay Time		25	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency and external bus cycles. Insert a wait state or lower the operation frequency, $f_{(BCLK)}$, if the calculated value is negative.

$$t_{ac1(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, m=(bx2)+1)$$

$$t_{ac1(AD-DB)} = \frac{10^9 \times n}{f_{(BCLK)}} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, n=a+b)$$

$$t_{ac2(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, m=(bx2)-1)$$

$$t_{ac2(AD-DB)} = \frac{10^9 \times p}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, p=\{(a+b-1) \times 2\}+1)$$

$$V_{CC1}=V_{CC2}=3.3V$$

Timing Requirements

($V_{CC1}=V_{CC2}=3.0$ to $3.6V$, $V_{SS}=0V$ at $T_{opr}=-20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.34 Timer B Input (Count Source Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time (counted on one edge)	100		ns
$t_{w(TBH)}$	TBiIN Input High ("H") Width (counted on one edge)	40		ns
$t_{w(TBL)}$	TBiIN Input Low ("L") Width (counted on one edge)	40		ns
$t_{c(TB)}$	TBiIN Input Cycle Time (counted on both edges)	200		ns
$t_{w(TBH)}$	TBiIN Input High ("H") Width (counted on both edges)	80		ns
$t_{w(TBL)}$	TBiIN Input Low ("L") Width (counted on both edges)	80		ns

Table 5.35 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time	400		ns
$t_{w(TBH)}$	TBiIN Input High ("H") Width	200		ns
$t_{w(TBL)}$	TBiIN Input Low ("L") Width	200		ns

Table 5.36 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time	400		ns
$t_{w(TBH)}$	TBiIN Input High ("H") Width	200		ns
$t_{w(TBL)}$	TBiIN Input Low ("L") Width	200		ns

Table 5.37 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(AD)}$	$\overline{AD_{TRG}}$ Input Cycle Time (required for trigger)	1000		ns
$t_{w(ADL)}$	$\overline{AD_{TRG}}$ Input Low ("L") Width	125		ns

Table 5.38 Serial I/O

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi Input Cycle Time	200		ns
$t_{w(CKH)}$	CLKi Input High ("H") Width	100		ns
$t_{w(CKL)}$	CLKi Input Low ("L") Width	100		ns
$t_{d(C-Q)}$	TxDi Output Delay Time		80	ns
$t_{h(C-Q)}$	TxDi Hold Time	0		ns
$t_{su(D-C)}$	RxDi Input Setup Time	30		ns
$t_{h(C-Q)}$	RxDi Input Hold Time	90		ns

Table 5.39 External Interrupt $\overline{INTi}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ Input High ("H") Width	250		ns
$t_{w(INL)}$	$\overline{INTi}$ Input Low ("L") Width	250		ns

5.2 Electrical Characteristics (M32C/84T)

Table 5.42 Absolute Maximum Ratings

Symbol	Parameter		Condition	Value	Unit
V _{CC1} , V _{CC2}	Supply Voltage		V _{CC1} =V _{CC2} =AV _{CC}	-0.3 to 6.0	V
AV _{CC}	Analog Supply Voltage		V _{CC1} =V _{CC2} =AV _{CC}	-0.3 to 6.0	V
V _I	Input Voltage	RESET, CNV _{SS} , BYTE, P60-P67, P72-P77, P80-P87, P90-P97, P100-P107, P140-P146, P150-P157 ⁽¹⁾ , V _{REF} , X _{IN}		-0.3 to V _{CC1} +0.3	V
		P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P110-P114, P120-P127, P130-P137 ⁽¹⁾		-0.3 to V _{CC2} +0.3	
		P70, P71		-0.3 to 6.0	
V _O	Output Voltage	P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P140-P146, P150-P157 ⁽¹⁾ , X _{OUT}		-0.3 to V _{CC1} +0.3	V
		P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P110-P114, P120-P127, P130-P137 ⁽¹⁾		-0.3 to V _{CC2} +0.3	
		P70, P71		-0.3 to 6.0	
P _d	Power Dissipation		T _{opr} =25° C	500	mW
T _{opr}	Operating Ambient Temperature	during CPU operation	T version	-40 to 85	° C
		during flash memory program and erase operation		0 to 60	
T _{stg}	Storage Temperature			-65 to 150	° C

NOTES:

1. P11 to P15 are provided in the 144-pin package only.

VCC1=VCC2=5V

Table 5.44 Electrical Characteristics (Continued)
(VCC1=VCC2=4.2 to 5.5V, VSS=0V at Topr = -40 to 85°C (T version),
f(BCLK)=32MHz unless otherwise specified)

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min.	Typ.	Max.	
Icc	Power Supply Current	In single-chip mode, output pins are left open and other pins are connected to Vss.		28	50	mA
				430		μA
				25		μA
				10		μA
				0.8	5	μA
					50	μA

NOTES:

1. Value is obtained when setting the FMSTP bit in the FMR0 register to "1" (flash memory stopped).

$$V_{CC1}=V_{CC2}=5V$$

Table 5.47 Flash Memory Version Electrical Characteristics(V_{CC1}=4.5 to 5.5V, 3.3 to 3.6V at T_{opr}= 0 to 60°C unless otherwise specified)

Symbol	Parameter	Standard			Unit
		Min.	Typ.	Max.	
-	Program and Erase Endurance ⁽²⁾	100			cycles
-	Word Program Time (V _{CC1} =5.0V, T _{opr} =25° C)		25	200	μs
-	Lock Bit Program Time		25	200	μs
-	Block Erase Time (V _{CC1} =5.0V, T _{opr} =25° C)	4-Kbyte Block	0.3	4	s
		8-Kbyte Block	0.3	4	s
		32-Kbyte Block	0.5	4	s
		64-Kbyte Block	0.8	4	s
-	All-Unlocked-Block Erase Time ⁽¹⁾			4 x <i>n</i>	s
t _{PS}	Wait Time to Stabilize Flash Memory Circuit			15	μs
-	Data Hold Time (T _{opr} =-40 to 85 ° C)	10			years

NOTES:

1. *n* denotes the number of block to be erased.

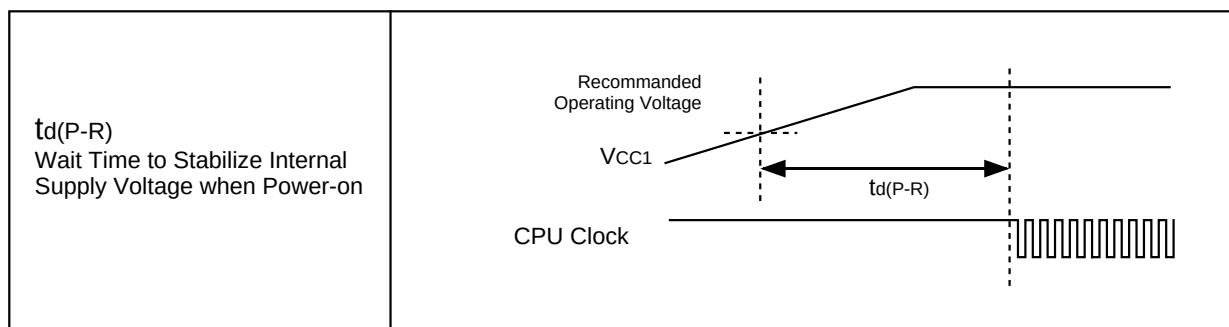
2. Number of program-erase cycles per block.

If Program and Erase Endurance is *n* cycle (*n*≠100), each block can be erased and programmed *n* cycles.

For example, if a 4-Kbyte block A is erased after programming a word data 2,048 times, each to a different address, this counts as one program and erase endurance. Data can not be programmed to the same address more than once without erasing the block. (rewrite prohibited).

Table 5.48 Power Supply Timing

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{d(P-R)}	Wait Time to Stabilize Internal Supply Voltage when Power-on	V _{CC1} =3.0 to 5.5V			2	ms

**Figure 5.11 Power Supply Timing Diagram**

